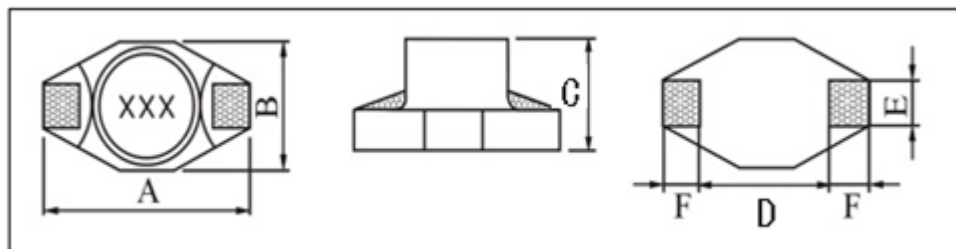


1、产品概要 / Outline

- ◆ 采用铁合金材料热喷涂技术，具有高通流和低损耗特性
- ◆ 闭合磁路的设计减少了漏磁通
- ◆ 较优的电磁兼容性和高能量储存
- ◆ 较大的电感值范围
- ◆ 工作温度：-40°C ~ +125°C
- ◆ 主要应用于医疗仪器、智能手机、平板电脑、VR 虚拟现实、便携式游戏机、智能穿戴等



2、外观尺寸/ Appearance size 单位:mm



A (max)	B (max)	C (max)	D	E	F
12.95	9.40	3.50	7.62	2.54	2.54

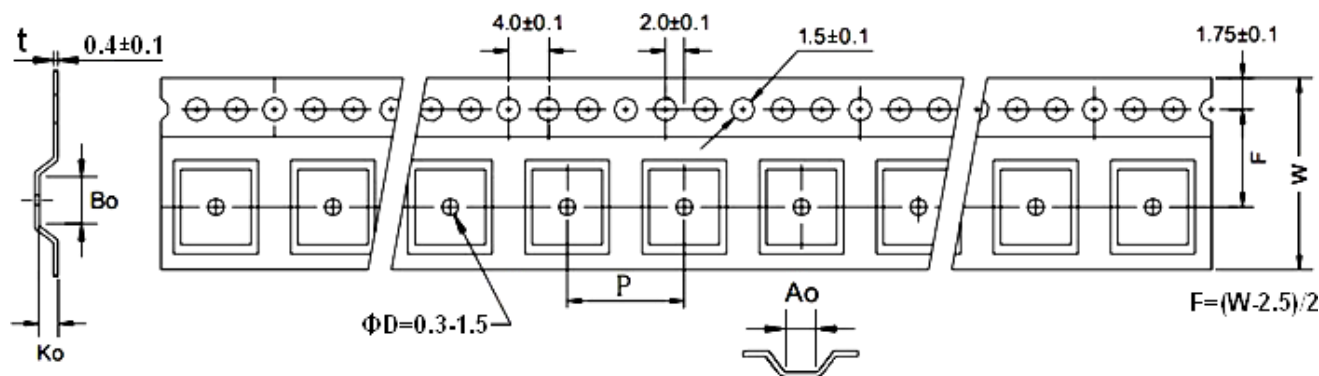
3、电气特性/Electrical characteristics

型号/NO	L/uH	DCR (mΩ)	Isat(A)	Irms(A)
CDC3310-100M	10	110	2.12	2.40
CDC3310-150M	15	130	2.00	2.20
CDC3310-180M	18	150	1.85	2.00
CDC3310-220M	22	180	1.65	1.80
CDC3310-330M	33	230	1.52	1.60
CDC3310-390M	39	260	1.40	1.50
CDC3310-470M	47	300	1.35	1.40
CDC3310-560M	56	350	1.12	1.30
CDC3310-680M	68	390	0.85	1.00
CDC3310-101K	100	450	0.80	0.95
CDC3310-151K	150	660	0.76	0.90
CDC3310-181K	180	760	0.68	0.80
CDC3310-221K	220	840	0.55	0.70
CDC3310-331K	330	940	0.50	0.65
CDC3310-391K	390	1200	0.45	0.60
CDC3310-471K	470	1400	0.40	0.55
CDC3310-561K	560	1900	0.45	0.50
CDC3310-681K	680	2100	0.38	0.45

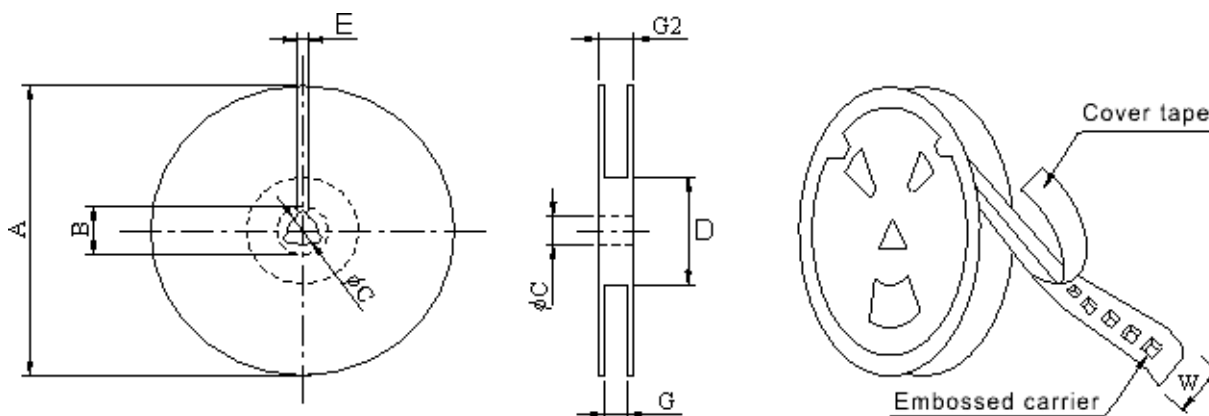
注释

- ◆ K 表示电感值的公差为±10%，M 表示电感值的公差为±20%
- ◆ K said inductance tolerance is ±10%, M said inductance tolerance is ± 20%
- ◆ 所有数据基于环境温度 25°C条件下测试
- ◆ All data is based on testing at an ambient temperature of 25 °C
- ◆ 测试条件：100KHz/0.25V
- ◆ 本页面未能录入全部或最新的数据，请您在订购前向本公司咨询精准参数及样品。
- ◆ We were unable to input all or the latest data on this page. Please consult our company for accurate parameters and samples before placing an order.

4 包装规格/ Packaging specifications 单位/mm



型号	Ao	Bo	Ko	P	W
CDC1680	4.8±0.1	7.2±0.1	3.15±0.1	8.0±0.1	16.0±0.3
CDC3316	9.6±0.1	13.1±0.1	5.6±0.1	12.0±0.1	24.0±0.3
CDC3340	9.4±0.1	13.0±0.1	11.5±0.1	16.0±0.1	24.0±0.3
CDC5022	15.7±0.1	19.0±0.1	7.2±0.1	20.0	32.0±0.3



型号	Quantity	A	B	C	D	E	G	G2
CDC1680	2000pcs	330±2.0	20.5Typ.	13.0±0.5	100Typ.	2.0±0.5	16.5±0.5	22.40Max.
CDC3316	1000pcs	330±2.0	20.5Typ.	13.0±0.5	100Typ.	2.0±0.5	24.5±0.5	30.40Max.
CDC3340	350pcs	330±2.0	20.5Typ.	13.0±0.5	100Typ.	2.0±0.5	24.5±0.5	30.40Max.
CDC5022	400pcs	330±2.0	20.5Typ.	13.0±0.5	100Typ.	2.0±0.5	32.5±0.5	38.40Max.

5、焊接/welding

• 焊接原材料 Soldering Materials

(a) 焊料：推荐使用 96.5Sn/3.0Ag/0.5Cu 焊料，或者采用 Sn 含量不超过 97%的锡合金焊料。

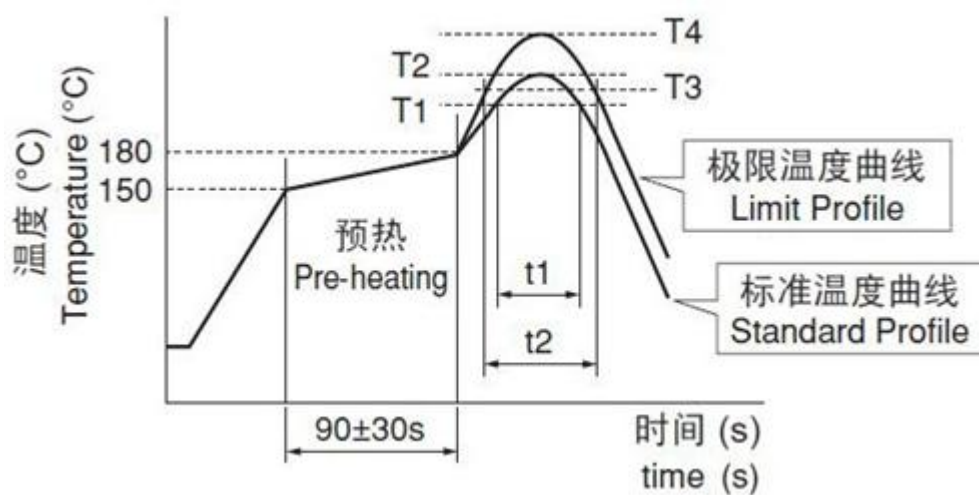
Solder: It is recommended to use 96.5Sn/3.0Ag/0.5Cu solder, or use Tin alloy solder with a Tin content not exceeding 97%.

(b) 助焊剂：推荐使用松香类助焊剂，请勿使用强酸性助焊剂（含氯量超过 0.2wt %），并且请勿使用水溶性助焊剂。

Flux: It is recommended to use rosin-based flux. Acidic flux (with chlorine content exceeding 0.2wt %) and water-soluble flux are forbidden.

• 焊接温度及要求 Soldering Temperature & Requirements

回流焊温度曲线 Reflow Soldering Temperature Profile



回流焊要求 Reflow Soldering Requirements

标准温度曲线Standard Profile				极限温度曲线Limit Profile			
加热Heating		峰值温度 PeakTemp (T2)	回流焊次 Cycle Of Reflow	加热Heating		峰值温度 Peak Temp. (T4)	回流焊次 数 Cycle Of Reflow
加热 Temp. (T1)	时间 Time(t)			温度 Temp. (T3)	时间 Time (t2)		
220°C	30~60s	245±3°C	≤2	230°C	≤60s	260°C/10s	1

6、其他

- ◆ 本产品为无铅，请采用无铅环境作业
- ◆ Other: Our company's products are lead-free, please operate in a lead-free environment
- ◆ 由于页面限制，更多资料请联系我司
- ◆ Due to page limitations, please contact our company for more information
- ◆ 在过载电流等不正常条件下，本电感产品无自我保护功能。
- ◆ Under abnormal conditions such as overload current, this inductor product has no self-protection function.